



2814
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DOCKET NO.: 8543-004-27 CIP

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

Re: Serial No.: 08/825,360
Applicant(s): Marvin LIAO, et al.
Filing Date: March 28, 1997
For: INTERCONNECT STRUCTURE FOR USE IN AN INTEGRATED
CIRCUIT
Group Art Unit: 2814
Examiner: Tuan N. Quach

SIR:

Attached hereto for filing are the following papers:

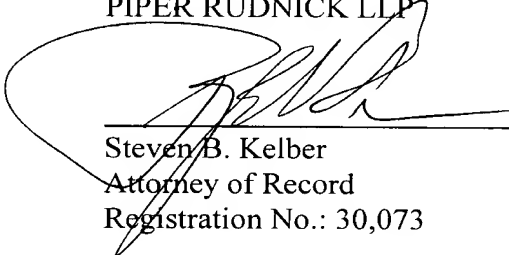
FEE TRANSMITTAL
INFORMATION DISCLOSURE STATEMENT
STATEMENT OF RELEVANCY
FORM PTO 1449
CITED DOCUMENTS (25)

RECEIVED
SEP 30 2002
TECHNOLOGY CENTER 2800

Our check in the amount of \$ 180.00 is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R. 1.136 for any necessary extension of time to make the filing of the attached documents timely, please charge or credit the difference to Deposit Account No. 50-1442. Further, if these papers are not considered timely filed, then a request is hereby made under 37 C.F.R. 1.136 for the necessary extension of time. A duplicate copy of this sheet is enclosed.

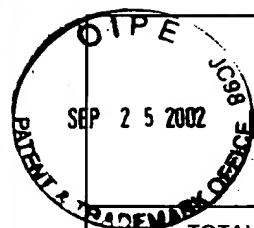
Respectfully submitted,

PIPER RUDNICK LLP



Steven B. Kelber
Attorney of Record
Registration No.: 30,073

Perry E. Van Over
Registration No.: 42,197



FEE TRANSMITTAL

Docket No.	8543-004-27 CIP
Serial No.	08/825,360
Filing Date	March 28, 1997
Inventor(s)	Marvin LIOA, et al.
Group Art Unit	2814
Examiner	Tuan N. QUACH

TOTAL AMOUNT OF PAYMENT

\$180.00

1. <input type="checkbox"/> Applicant claims small entity status.										FEE CALCULATION (continued)						
<input checked="" type="checkbox"/> Charge any UNDERPAYMENT or credit any OVERPAYMENT in the indicated fees to Deposit Account No. 50-1442.										3. ADDITIONAL FEES						
<input type="checkbox"/> Charge the indicated fees to Deposit Account No. 50-1442.										Large Entity		Small Entity		Fee Description		
2. <input checked="" type="checkbox"/> Check enclosed.										Fee Code	Fee (\$)	Fee Code	Fee (\$)		Fee Paid	
FEE CALCULATION										105	130	205	65	Surcharge-late filing fee or oath		
1. BASIC FILING FEE										127	50	227	25	Surcharge-late provisional filing fee or cover sheet		
Large Entity		Small Entity		Fee Description				139	130	139	130	Non-English specification				
Fee Code	Fee (\$)	Fee Code	Fee (\$)					Fee Paid	147	2520	147	2520	Ex parte reexam. fee			
101	740	201	370	Utility filing fee					115	110	215	55	1-mo. ext. of time			
106	330	206	165	Design filing fee					116	400	216	200	2-mo. ext. of time			
107	510	207	255	Plant filing fee					117	920	217	460	3-mo. ext. of time			
108	740	208	370	Reissue filing fee					118	1440	218	720	4-mo. ext. of time			
114	160	214	80	Provisional filing fee					128	1960	228	980	5-mo. ext. of time			
SUBTOTAL (1)								\$0.00	119	320	219	160	Notice of Appeal			
2. EXTRA CLAIM FEES										120	320	220	160	Appeal Brief		
tot. claims			-	20*	=	0	x	\$18	=	0	121	280	221	140	Request for Oral Hearing	
ind. claims			-	3*	=	0	x	\$84	=	0	142	1280	242	640	Utility/Reissue Issue Fee	
<input type="checkbox"/> Multiple Dependent Claims		\$280						=		143	460	243	230	Design Issue Fee		
Large Entity		Small Entity		Fee Description				144	620	244	310	Plant Issue Fee				
Fee Code	Fee (\$)	Fee Code	Fee (\$)					122	130	122	130	Petitions to the Commissioner				
103	18	203	9	Claims in excess of 20					126	180	126	180	IDS Submission	180.00		
102	84	202	42	Independent claims in excess of 3					581	40	581	40	Assignment			
104	280	204	140	Multiple dependent claim, if not paid					179	740	279	370	For Filing RCE			
109	84	209	42	*Reissue independent claims over original patent					169	900	169	900	Expedited Design			
110	18	210	9	*Reissue claims in excess of 20 and over original patent				OTHER (indicate below):								
SUBTOTAL (2)								\$0.00								
* or number previously paid, if greater; For Reissues, see above										SUBTOTAL (3)				\$180.00		

Name	Steven B. Kelber	Registration No.	30,073
Signature		Date	Sept 25, 2002
Name	Perry E. Van Over	Registration No.	42,197

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION: Marvin LIAO, et al.

GROUP ART UNIT: 2814

SERIAL NUMBER: 08/825,360

EXAMINER: Tuan N. Quach

FILED: March 28, 1997

FOR: INTERCONNECT STRUCTURE FOR USE IN AN INTEGRATED CIRCUIT

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. 1.97Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Applicant(s) wish(es) to disclose the following information.

REFERENCES

- ☒ Applicant(s) wish(es) to make of record the documents listed on the attached Form PTO-1449. Copies of the listed documents are attached, where required, as are either statements of relevancy or any readily available full or partial English translations of any non-English-language documents.

RELATED CASES

- ☐ Attached is a list of Applicant's(s') pending applications and issued patents which may be related to the present application. Copies of the documents, where required, are attached along with Form PTO-1449.

CERTIFICATION

The undersigned certifies that

- ☐ each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign or international patent office in a counterpart foreign or international application for the first time (to the knowledge of the undersigned, having made reasonable inquiry) not more than three months prior to the filing of this statement.
- ☐ no item of information contained in this Information Disclosure Statement was cited in a communication from a foreign or international patent office in a counterpart foreign or international application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 C.F.R. 1.56(c) more than three months prior to the filing of this statement.

BASIS FOR CONSIDERATION

This Information Disclosure Statement is filed:

- ☐ without fee and within three months of the filing date of the application.
- ☐ without fee and within three months of the date of entry of the U.S. national stage.
- ☐ without fee and before the mailing date of a first Office Action on the merits (to the knowledge of the undersigned).
- ☐ without fee and with the appropriate certification above.
- ☐ without fee and with a new CPA application.
- ☐ without fee and with a Request for Continued Examination.
- ☒ with fee and before the mailing date of any of a Final Office Action, Notice of Allowance or an action that otherwise closes prosecution (to the knowledge of the undersigned).
- ☐ with fee, appropriate certification above, and before payment of the Issue Fee.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to Deposit Account No. 50-1442.

09/26/2002 KZENDIE 00000022 08825360

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180.00 OP

Respectfully submitted,

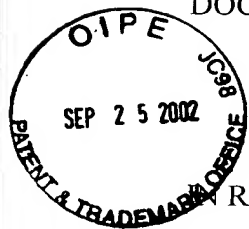
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SEP 25 2002
PATENT & TRADEMARK OFFICE 8600



DOCKET NO. 8543-004-27 CIP

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RE APPLICATION OF: Marvin LIOA, et al.

ART UNIT: 2814

SERIAL NO.: 08/825,360

EXAMINER: Tuan N. Quach

FILING DATE: March 28, 1997

FOR: INTERCONNECT STRUCTURE FOR USE IN AN INTEGRATED CIRCUIT

STATEMENT OF RELEVANCY

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

This Statement of Relevancy is herewith submitted with the concurrently filed Information Disclosure Statement. The below cited German language article is submitted for consideration in the examination of the present application. An English language translation of the article could not be located.

Rie, K.-T., et al., "Abscheidung von Titannitridschichten mittels Plasma-CBD",
HTM, 42, 153-159 (1987).

The above cited article is directed to plasma enhanced chemical vapor deposition (CVD) of hard coatings. The article discloses equipment and methods which permits the deposition temperature of the CVD process of titanium nitride to be lowered to 500 - 600 ° C by use of direct current glow discharge. The pulsed plasma CVD process discussed in the paper suggest the possibility for process parameter optimization. As such, while the *Rie* reference teaches background knowledge of such processes, it fails to teach or suggest the Applicants' present invention.

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Consideration of the above cited references with all Information Disclosure Materials
concurrently filed is respectfully requested.

Respectfully submitted,

PIPER RUDNICK LLP

A handwritten signature in black ink, appearing to read 'S. Kelber', is written over a horizontal line.

Steven B. Kelber
Registration No. 30,073
Attorney of Record

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Perry E. Van Over
Registration No. 42,197

Form PTO 1449 U.S. DEPARTMENT OF
(Modified) COMMERCE
PATENT AND TRADEMARK
OFFICE

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08/825,360

APPLICANT

Marvin LIAO, et al.

FILING DATE

March 28, 1997

GROUP ART UNIT

2814

LIST OF REFERENCES CITED BY APPLICANT
(Use Several Sheets if Necessary)

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA	4,173,661	11/1979	Bourdon			
	AB	4,420,498	12/1983	Hirose, et al.			
	AC	4,486,462	12/1984	Asahi, et al.			
	AD	4,965,090	10/1990	Gärtner, et al.			
	AE	5,017,403	5/1991	Pang, et al.			
	AF	5,314,603	5/1994	Sugiyama, et al.			
	AG	5,480,684	1/1996	Sandhu			
	AH	5,518,936	5/1996	Yamamoto, et al.			
	AI	5,576,071	11/1996	Sandhu			
	AJ	5,693,541	12/1997	Yamazaki, et al.			
	AK	5,716,870	2/1998	Foster, et al.			
	AL	5,747,116	5/1998	Sharan, et al.			
	AM	5,754,390	5/1998	Sandhu, et al.			
	AN	5,773,363	6/1998	Derderian, et al.			
	AO	6,251,758 B1	6/2001	Chern, et al.			

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO	
	AP	EP0397131 A2	11/1990	Europe	X	
	AQ	EP0711846 A1	5/1996	Europe	X	
	AR	JP63-229814	9/1988	Japan		X**
	AS	JP3-135018	6/1991	Japan		X**
	AT	JP4-100221	4/1992	Japan		X**
	AU	JP6-120152	4/1994	Japan		X**

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

	AV	Wang, C.K., et al., "Optimization of PVD Ti/CVD TiN Liner for 0.35 μ m Tungsten Plug Technology", Mat. Res. Society Symp. Proc., Vol. 427, p. 383-387 (1996).
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EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

**English Abstract Provided

Form PTO 1449 U.S. DEPARTMENT OF
(Modified) COMMERCE
PATENT AND TRADEMARK
OFFICE

DOCKET NO.

8543-004-27 CIP

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APPLICANT

Marvin LIAO, et al.

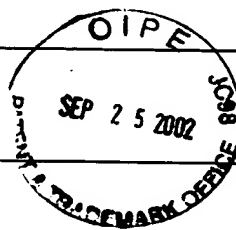
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(Use Several Sheets if Necessary)

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EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AW						
	AX						
	AY						
	AZ						
	BA						
	BB						
	BC						
	BD						
	BE						
	BF						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO
	BG				
	BH				
	BI				
	BJ				
	BK				

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

BL	Danek, M., et al., "Resistivity Reduction and Chemical Stabilization of Organometallic Chemical Vapor Deposited Titanium Nitride by Nitrogen RF Plasma", Appl. Phys. Lett. 68 (7), (1996).
BM	Eizenberg, M., "Chemical Vapor Deposition of TiN for ULSI Applications", Mat. Res. Soc. Symp. Proc., Vol. 427, p. 325-335 (1996).
BN	Rie, K.-T., et al., "Abscheidung von Titannitridschichten mittels Plasma-CVD", HTM, 42, 153-159 (1987).
BO	
BP	

EXAMINER

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